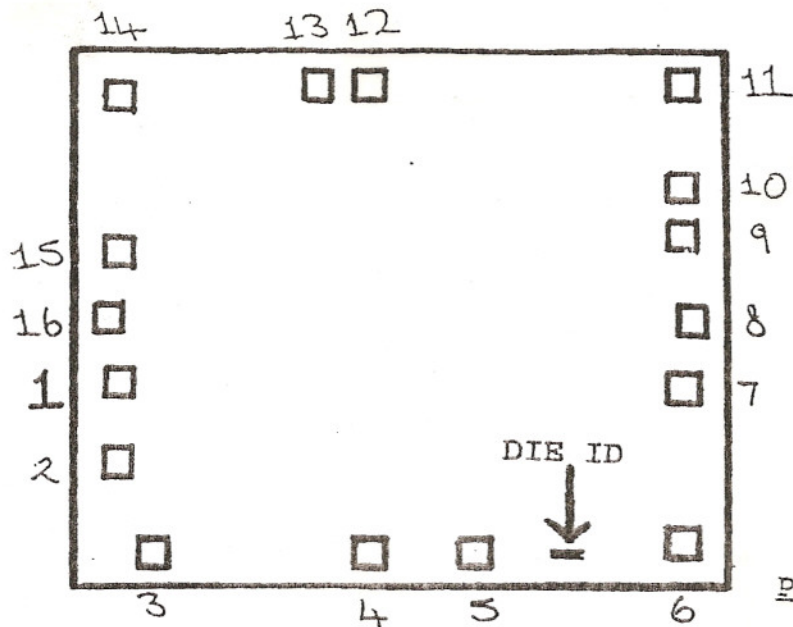




# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad	Function	Pad	Function
1	T <sub>1A</sub>	9	Q <sub>B</sub> OUT
2	T <sub>2A</sub>	10	Q <sub>B</sub> OUT
3	C <sup>DA</sup>	11	B <sub>B</sub> INPUT
4	A <sub>A</sub> INPUT	12	A <sub>B</sub> INPUT
5	B <sub>A</sub> INPUT	13	C <sup>DB</sup>
6	Q <sub>A</sub> OUT	14	T <sub>2B</sub>
7	Q <sub>A</sub> OUT	15	T <sub>1B</sub>
8	V <sub>SS</sub>	16	V <sub>DD</sub>

**Topside Metal: Al**  
**Backside: Si**  
**Backside Potential:**  
**Mask Ref:**  
**Bond Pads (Mils):**

<b>APPROVED BY:</b>	<b>DIE SIZE (Mils): 89 x 77</b>	<b>DATE: 3/13/00</b>
<b>MFG: National</b>	<b>THICKNESS: 15</b>	<b>P/N: CD4538B</b>

DG 10.1.2  
 Rev A 3-4-99